

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (previously presented) Device (1) for wet treating a flat plate-like substrate (W) comprising:

a spinchuck (2) for holding and rotating the substrate about a rotation axis (A);

at least one dispenser (3) for dispensing a liquid onto at least one surface (W) of said substrate;

a liquid collector (4) circumferentially surrounding said spin-chuck for collecting liquid, which is spun off the substrate during rotation, with at least two collector levels (L1, L2), for separately collecting liquids in different collectors (41, 42);

lifting means (H) for moving spin-chuck (2) relative to liquid collector (4) substantially along the rotation axis (A);

at least two exhaust levels (E1, E2) for separately collecting gas from the interior (40) of the liquid collector (4);

at least one exhaust influencing means (71), which is associated with at least one of said at least two exhaust

levels, for selectively varying gas flow conditions in at least one of said at least two exhaust levels (E1, E2).

2. (previously presented) Device according to claim 1, wherein the at least one exhaust influencing means (71) is a flow control modulating valve.

3. (original) Device according to claim 1, wherein the at least one exhaust influencing means (71) is a closing valve, whereby one of the at least two exhaust levels can be closed.

4. (original) Device according to claim 1 comprising controlling means whereby the at least one exhaust influencing means is controlled in dependence of the relative position of spin-chuck to liquid collector.

5. (original) Device according to claim 1, wherein suction orifices (21, 22) of at least one of the exhaust level (E1, E2) are connected to one of the two collector levels (L1, L2).

6. (previously presented) Device according to claim 1, wherein at least one of said at least two exhaust levels

(E1, E2) is arranged above or below one of said at least two collector levels (L1, L2).

7. (Currently amended) Method of controlling the gas flow within a device (1) for wet treating a substrate (W), the device comprising a liquid collector and at least two exhaust levels for separately collecting gas from the interior of the liquid collector, characterized in selectively generating different gas flow conditions in at least two of said exhaust levels.

8. (original) Method according to claim 7 wherein the different gas flow conditions are selected in a way to achieve substantially the same gas pressure adjacent to the rotating substrate above and below said substrate.